Features

Applications: transmission, TDM networks, SDH, SONET, wireless communications, IEEE 1588v2, SyncE, STRATUM III, wireless backhaul, metro carrier Ethernet, femtocells, picocells

Holdover stability: ± 0.37 ppm over 24 h

Overall stability: ±4.60 ppm including 20 years aging

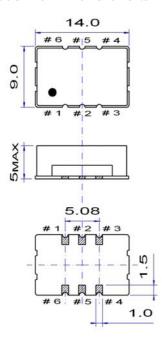
Output signal: HCMOS

Specification

| Parameter | Specification | |
|--|---|--|
| Frequency range | 10.0 ~ 100.0 MHz | |
| Standard frequencies | 10.0, 12.80, 16.3840, 19.440, 20.0, 25.0, 26.0 & 38.880 MHz | |
| Frequency stability: | ≤ ±4.60 ppm | overall stability including 20 years aging |
| vs. temperature | ≤ ±0.28 ppm | -40 ~ +85 °C |
| vs. aging | ≤ ±3.0 ppm | 20 years |
| Holdover stability (1) | ≤ ±0.37 ppm | over 24 hours |
| Frequency tolerance ex. factory | ≤ ±0.50 ppm | @ +25 °C |
| Supply voltage | +3.3 V or +5.0 V | ±5 % |
| Supply current | < 6 mA | |
| Output signal | HCMOS | |
| Output load | 15 pF | ±5 % |
| Tri-state function | pin #2 high or open pin #2 low | pin #4 → oscillation pin #4 → high impedance |
| Phase noise @ 12.8 MHz carrier frequency | -145 dBc/Hz | @ 10 kHz |
| Operating temperature range | 0 ~ +70 °C | indoor use |
| | -40 ~ +85 °C | outdoor use |
| Storage temperature range | -55 ~ +125 °C | |
| Packaging units | tape & reel tape only | 500 pieces < 500 pieces |
| Customer specifications on request | | |

⁽¹⁾ Including: frequency stability, vs temperature, supply change of ±5 % and aging over 24 hours

Outline Dimensions & PIN Function & Solder Pattern



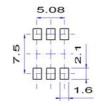
Pin function

1 not connected # 2 Tri-state or not connected # 3 GND

4 Output # 5 not connected

#6 Vdc

Example for solder pattern



Do not design any conductive path between the pattern

Example for IR reflow soldering temperature

